

## AMENDMENTS TO THE SPECIFICATION

1. Please add the Cross-Reference to Related Application(s) section after the Title beginning on page 1, line 3, as follows:

### CROSS-REFERENCE TO RELATED APPLICATION(S)

This is a divisional of co-pending application serial number 10/055,094 filed January 23, 2002, which is hereby incorporated by reference herein.

2. Please replace the paragraph, which begins on page 3, line 15, with the following paragraph:

Figs. ~~6a through 6e~~6b and 6c show examples of the method of the invention of anchoring a heat spreader over the surface of a substrate, the substrates of the two representations are different.

3. Please replace the paragraph, which begins on page 3, line 20, with the following paragraph:

Figs. 8a through 8f show a second flow of creating a PBGA package using the anchoring method of the ~~invention, this first~~invention. This second method incorporates enhancing the conventional heat spreader attach tool.

4. Please replace the paragraph, which begins on page 6, line 26, with the following paragraph

The contact points 29, also referred to as anchor ~~posts~~posts, can be created using epoxy to which traces of silver have been added or solder paste or a solid metal.

5. Please replace the paragraph, which begins on page 6, line 28, with the following paragraph

Fig. 4 shows a cross section of the section 38, Fig. 1, the heat spreader standoff of the heat spreader 14, which highlights:

- a first surface of the heat spreader 14 is seated directly over a second surface of the substrate 12
- no adhesive glue is provided in the interface between the heat spreader 14 and substrate 12
- the heat spreader stand-off 38, and therewith the heat spreader 14, ~~a~~is seated over the second surface of substrate 12 by means of a positioning and anchoring post 31 that is pre-formed over the surface of substrate 12
- anchoring post 31 is centered with respect to and inserted through an opening 33 that has been provided for this purpose in the heat spreader stand-off 38
- 35 highlights the consistent seating height of the heat spreader 14, which is made possible by the direct contact between the heat spreader stand-off post 38 and the substrate 12, without any intervening layers of glue, paste and the like.

6. Please replace the paragraph, which begins on page 7, line 9, with the following paragraph

Fig. 5 shows a cross section ~~this~~that is identical to the cross section of Fig. 4 with exception of the addition of an optional layer 37 of electrically and/or thermally conductive material. This optional layer 37 provides for firmer seating and locking of the standoff 38, ~~in addition~~38. In addition, layer 37 enhances thermal conduction from the heat spreader 14 to the ~~surface of~~ substrate 12.

7. Please replace the paragraph, which begins on page 8, line 24, with the following paragraph:

Figs. 7a through 7g and 8a through 8f are provided to show the heat spreader attach processing steps of the invention before the molding is applied, these two sets of figures are differentiated as follows:

- Figs. 7a through 7g show the indicated flow, implemented by enhancing the die attach machine, and
- Figs. 8a through 8f show the indicated flow, implemented by enhancing the conventional die heat spreader attach machine.

8. Please amend the Abstract which begins on page 18, line 1, as follows which begins on the next page: